

Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P_PP	84	W	8/20μs, Per Fig. 2
Peak Pulse Current	I _{PP}	6	Α	8/20μs, Per Fig. 2
ESD Protection – Contact Discharge	V _{ESD_Contact}	±30	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V_{ESD_Air}	±30	kV	Standard IEC 61000-4-2

Thermal Characteristics

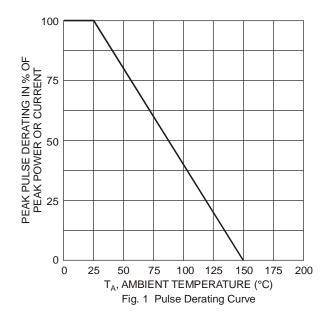
Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_{D}	380	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ hetaJA}$	327	°C/W
Operating Junction Temperature Range	TJ	-65 to +150	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C

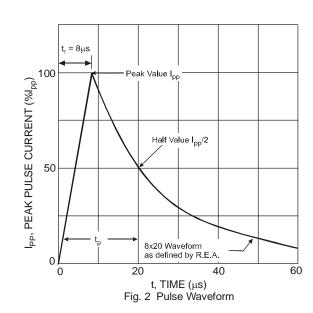
Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V _{RWM}	-	-	5.0	V	-
Breakdown Voltage	V_{BR}	6	7	8	V	I _R = 1.0mA
Reverse Leakage Current (Note 6)	I _R	-	10	100	nA	V _{RWM} = 5V
Clamping Voltage (Note 4)	VcL	-	7.0	9.0	V	$I_{PP} = 1A, t_p = 8/20 \mu S$
		-	8.7	10.7	V	$I_{PP} = 3A, t_p = 8/20\mu S$
		-	10.5	12.0	V	$I_{PP} = 5A, t_p = 8/20\mu S$
		-	11.5	14.0	V	$I_{PP} = 6A, t_p = 8/20\mu S$
Differential Resistance	R _{DIF}	-	0.2	-	Ω	$I_R = 1.0A$, $t_p = 8/20 \mu S$
Channel Input Capacitance	Ст	-	15	20	pF	V _{IN} = 0V, f = 1MHz (Channel to Pin 2)

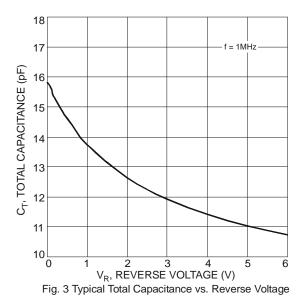
Notes:

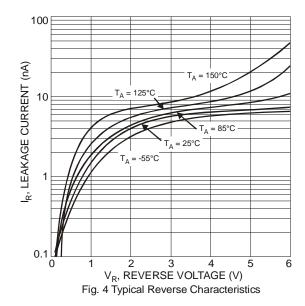
- 4. Measured from channel to pin 2; Non-repetitive current pulse per Fig. 2.
- 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.



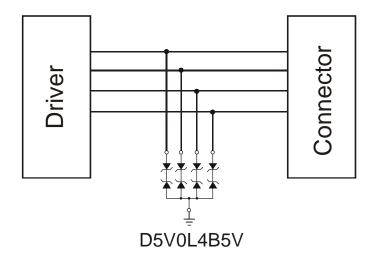






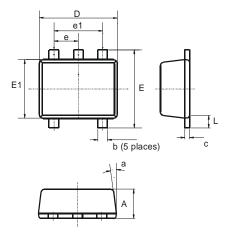


Typical Applications



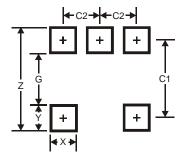


Package Outline Dimensions



SOT553					
Dim	Min	Max	Тур		
Α	0.55	0.60	0.60		
С	0.10	0.18	0.15		
D	1.50	1.70	1.60		
Е	1.55	1.70	1.60		
E1	1.10	1.25	1.20		
L	0.10	0.30	0.20		
b	0.15	0.30	0.20		
е	0.50 Typ				
e1	1.00 Typ				
а	6°	8°	7°		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Υ	0.5
C1	1.7
C2	0.5



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